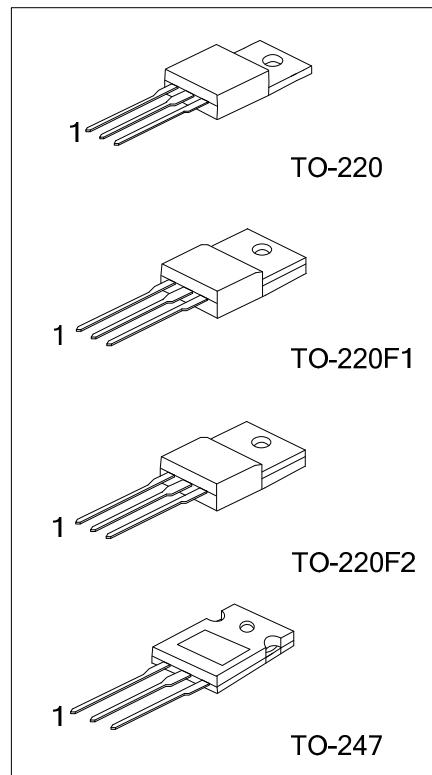
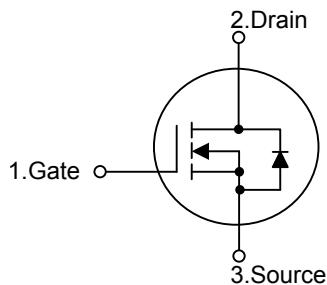


30NM65**Power MOSFET****30A, 650V N-CHANNEL
SUPER-JUNCTION MOSFET****■ DESCRIPTION**

The **UTC 30NM65** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at DC-DC, AC-DC converters for power applications.

■ FEATURES

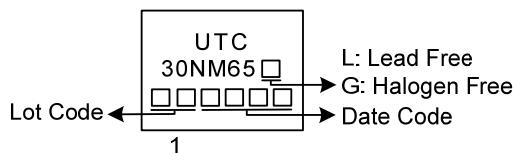
- * $R_{DS(ON)} < 0.14\Omega$ @ $V_{GS}=10V$, $I_D=15A$
- * High Switching Speed
- * 100% Avalanche Tested

■ SYMBOL**■ ORDERING INFORMATION**

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
30NM65L-T47-T	30NM65G-T47-T	TO-247	G	D	S	Tube
30NM65L-TA3-T	30NM65G-TA3-T	TO-220	G	D	S	Tube
30NM65L-TF1-T	30NM65G-TF1-T	TO-220F1	G	D	S	Tube
30NM65L-TF2-T	30NM65G-TF2-T	TO-220F2	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

30NM65G-T47-T 	(1) T: Tube (2) T47: TO-247, TA3: TO-220, TF1: TO-220F1, TF2: TO-220F2 (3) G: Halogen Free and Lead Free, L: Lead Free
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■ MARKING

■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	Continuous	I_D	30	A
	Pulsed (Note 2)	I_{DM}	90	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	737	mJ
Peak Diode Recovery dv/dt		dv/dt	7.8	V/ns
Power Dissipation	TO-220	P_D	265	W
	TO-220F1/TO-220F2		34	W
	TO-247		310	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Operating Temperature		T_{OPR}	-55 ~ +150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L = 47\text{mH}$, $I_{AS} = 5.6\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 30\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/TO-220F1	θ_{JA}	62.5	$^\circ\text{C/W}$
	TO-220F2		40	$^\circ\text{C/W}$
	TO-247			
Junction to Case	TO-220	θ_{JC}	0.47	$^\circ\text{C/W}$
	TO-220F1/TO-220F2		3.65	$^\circ\text{C/W}$
	TO-247		0.40	$^\circ\text{C/W}$

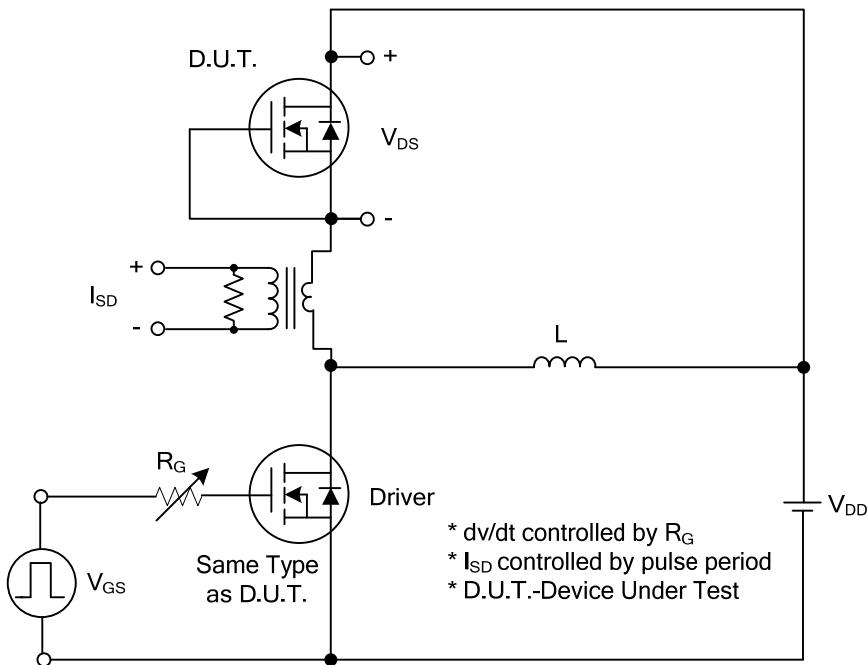
■ ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	650			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$		50		μA
Gate- Source Leakage Current	Forward	$V_{GS}=+30\text{V}, V_{DS}=0\text{V}$			+100	nA
	Reverse	$V_{GS}=-30\text{V}, V_{DS}=0\text{V}$			-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=15\text{A}$			0.14	Ω
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1.0\text{MHz}$		2575		pF
Output Capacitance	C_{OSS}			1435		pF
Reverse Transfer Capacitance	C_{RSS}			85		pF
SWITCHING PARAMETERS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=200\text{V}, V_{GS}=10\text{V}, I_D=30\text{A}, I_G=1\text{mA}$ (Note 1,2)		77.2		nC
Gate to Source Charge	Q_{GS}			18.8		nC
Gate to Drain Charge	Q_{GD}			30.8		nC
Turn-ON Delay Time (Note 1)	$t_{D(\text{ON})}$	$V_{DD}=30\text{V}, I_D=0.5\text{A}, R_G=25\Omega, V_{GS}=10\text{V}$ (Note 1,2)		95		ns
Rise Time	t_R			270		ns
Turn-OFF Delay Time	$t_{D(\text{OFF})}$			695		ns
Fall-Time	t_F			400		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Body-Diode Continuous Current	I_S				30	A
Maximum Body-Diode Pulsed Current	I_{SM}				90	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=30\text{A}, V_{GS}=0\text{V}$			1.4	V
Body Diode Reverse Recovery Time (Note 1)	t_{rr}	$I_S=30\text{A}, V_{GS}=0\text{V}, dI_F/dt=100\text{A}/\mu\text{s}$		540		ns
Body Diode Reverse Recovery Charge	Q_{rr}			10.5		μC

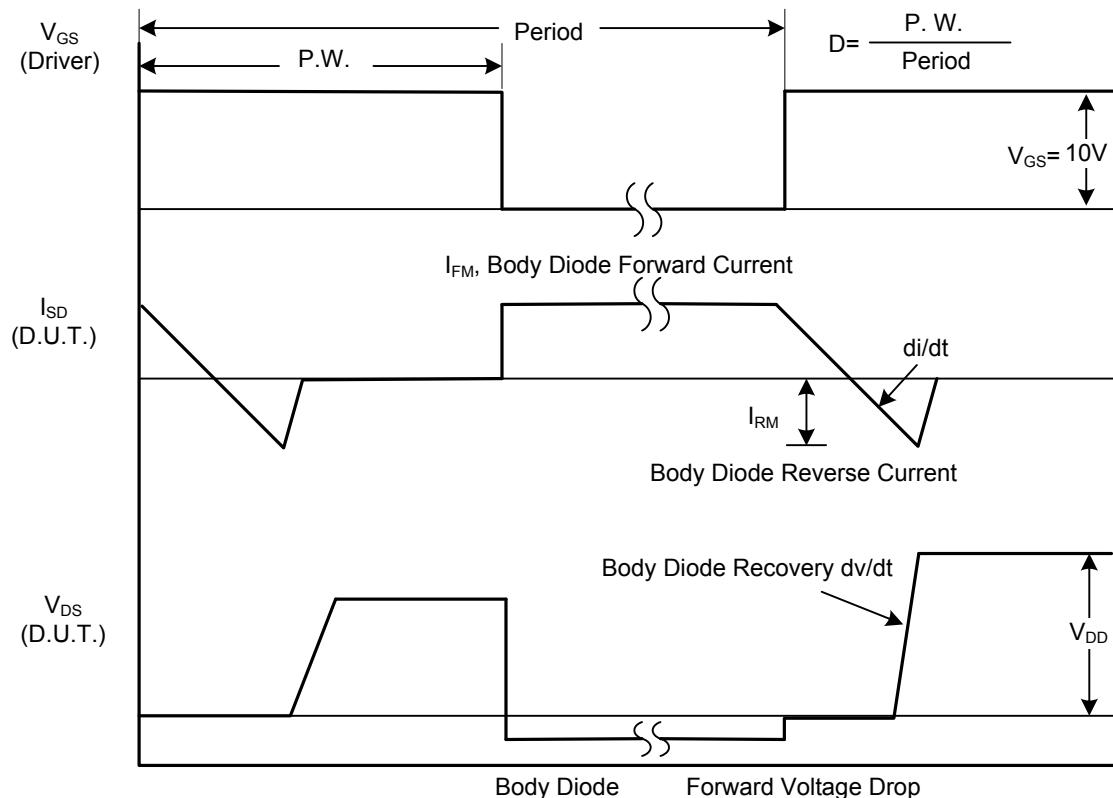
Notes: 1. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

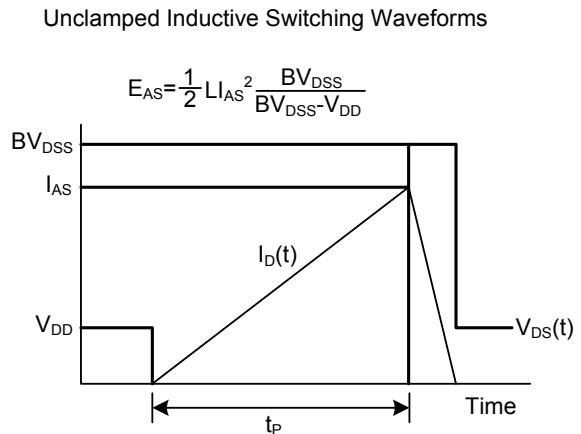
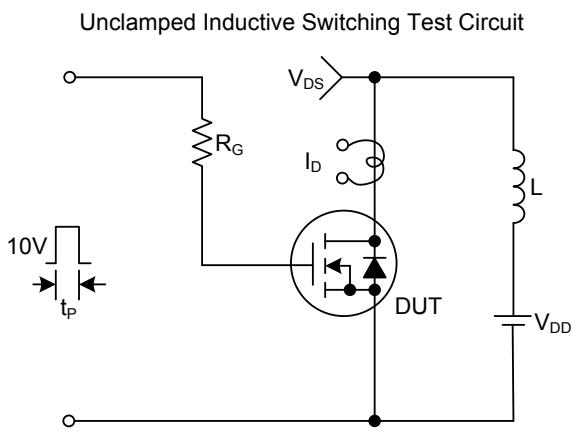
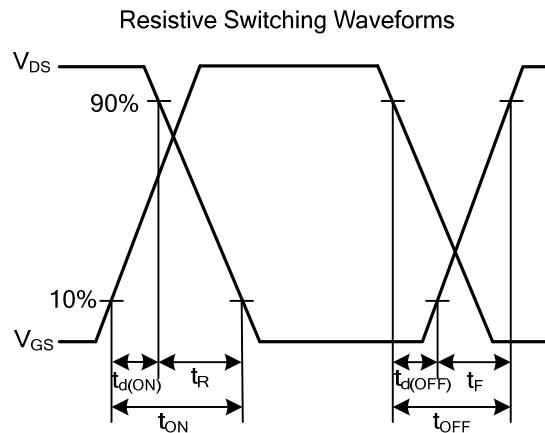
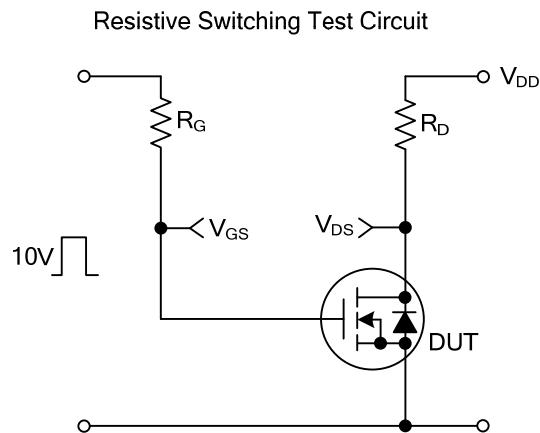
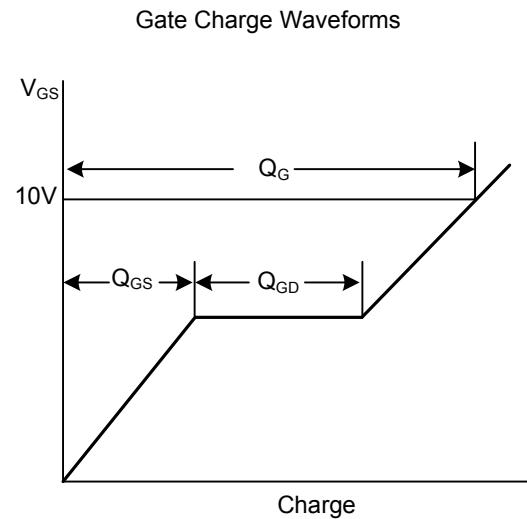
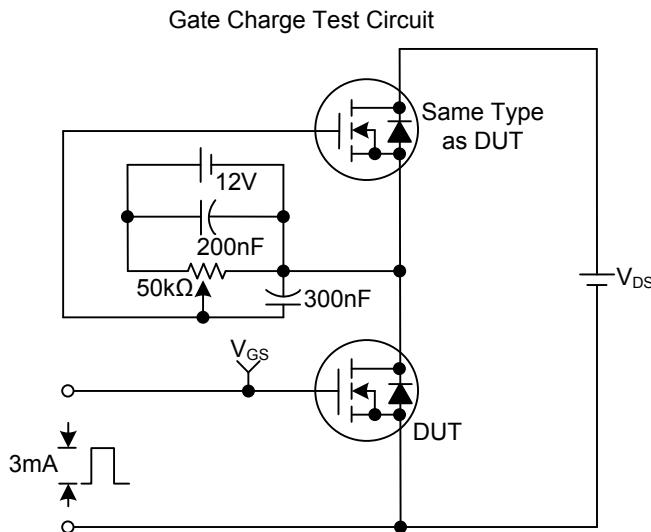


Peak Diode Recovery dv/dt Test Circuit

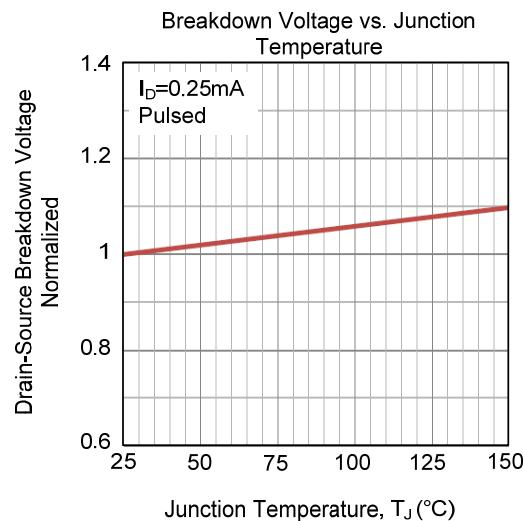
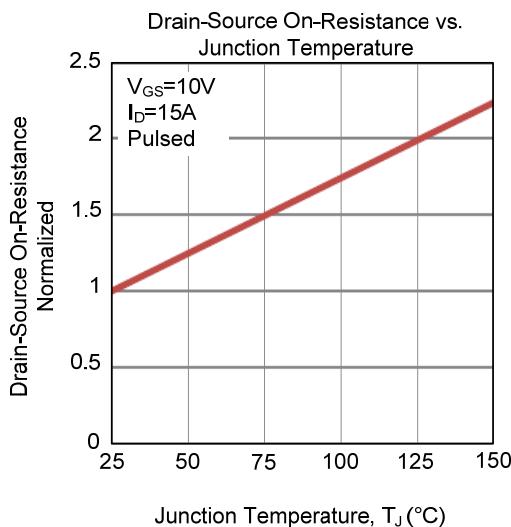
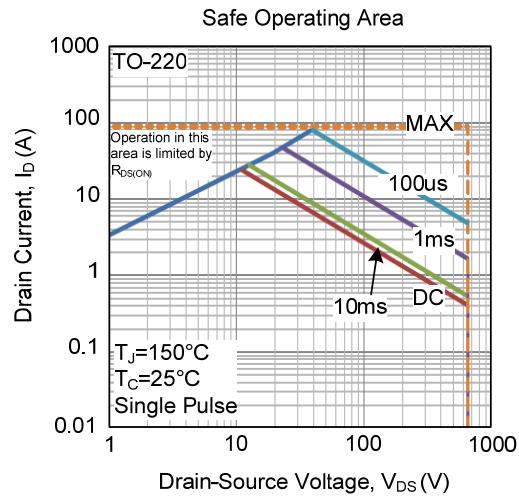
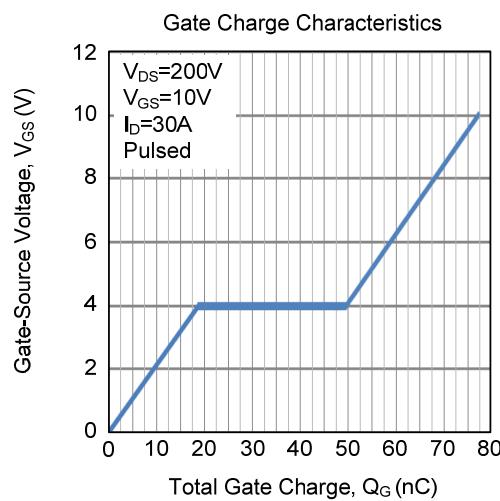
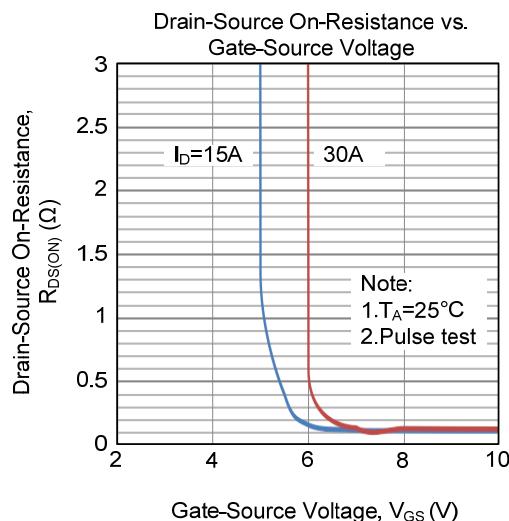
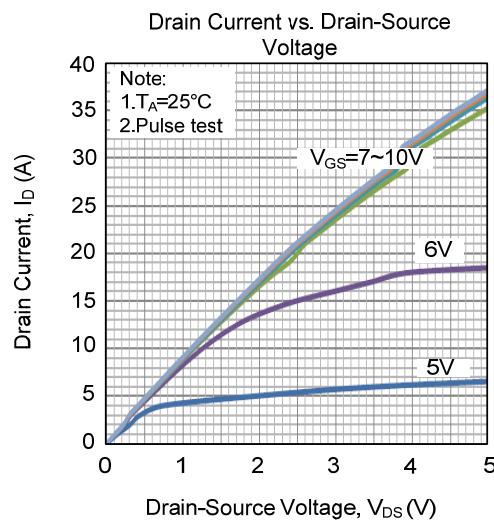


Peak Diode Recovery dv/dt Waveforms

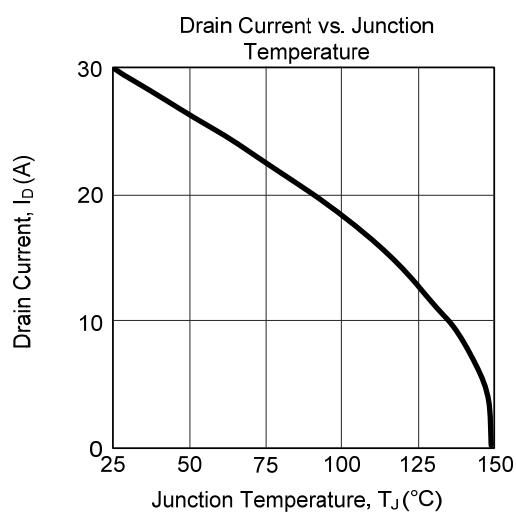
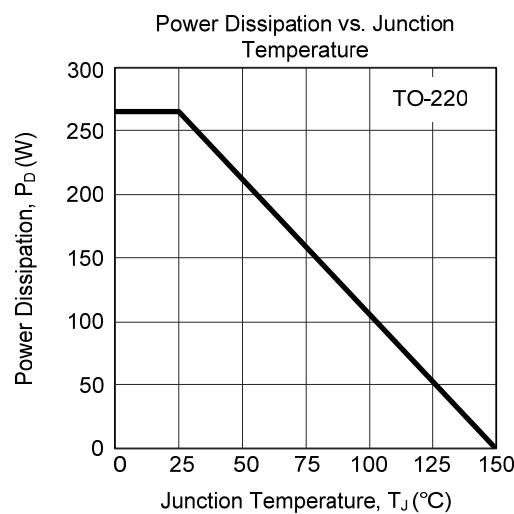
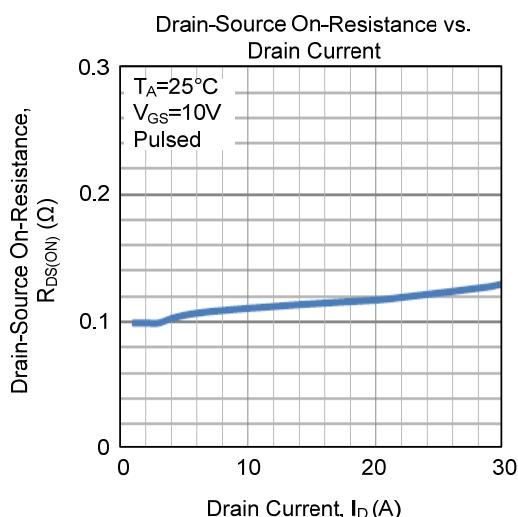
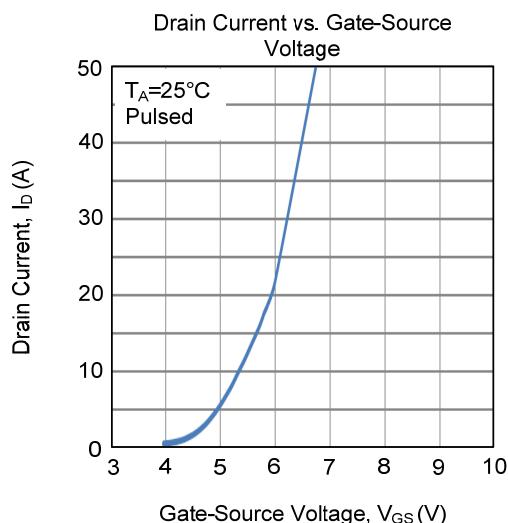
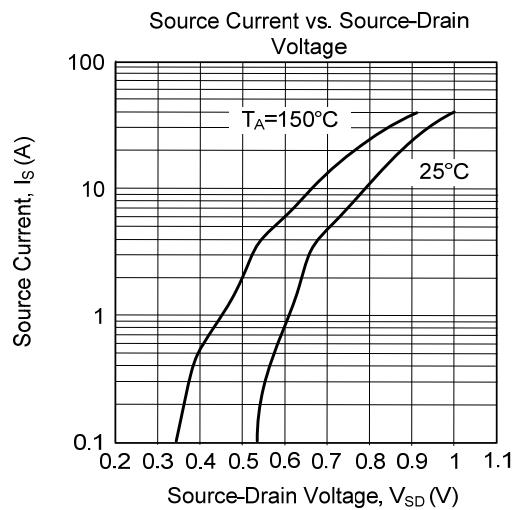
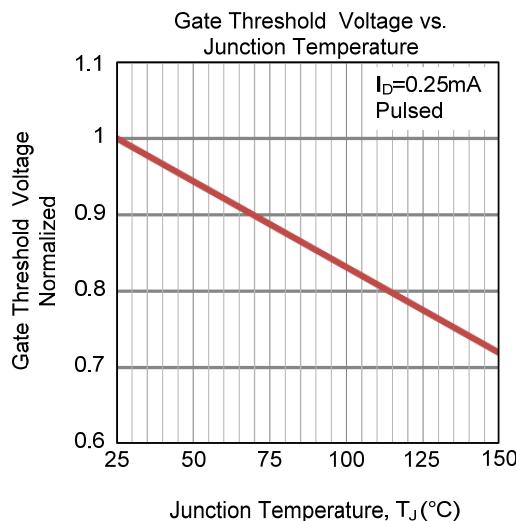
■ TEST CIRCUITS AND WAVEFORMS



■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



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